

SEMICON® EUROPA

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Global GAAC Summit



A. Aal
Semiconductor Strategy
Volkswagen AG, Munich, Germany



Biography

Andreas (IEEE SM / CRP) drove the semiconductor strategy & reliability assurance activities within the E/E development at Volkswagen, Germany, for many years, concentrating on technology capability enhancement of most advanced nodes incl. improved HW integration schemes as well as optimization of power electronics for automotive applications. He temporarily joint CARIAD SE between 2020 and 2022 as a system architect and product security officer focusing on semiconductor and SW driven innovations.

Wearing always one shoe from the semiconductor industry and the other one from the car OEM, he became a strong representative of the through-the-supply-chain-joint-development and collaboration approach also being rewarded with the EDA Achievement award 2020.

He has 24 years of experience with and within the semiconductor industry, has authored/co-authored over 40 publications on reliability and has given tutorials at IEEE IRPS and IIRW as well as invited and keynote speeches during various conferences and conventions.

His early collaboration activities began already in 2007 becoming the chair of the German VDE ITG group MN 5.6 on (f)WLR, reliability simulations and qualification. He is currently also chair of the European chapter of the SEMI Global Automotive Advisory Council (GAAC), member of the coordination team of the corresponding "European platform for automotive semiconductor requirements along the supply chain" hosted by the VDE ITG and member of the Bmbf industry advisory board on cyber security.

Driving the disruptive automotive transformation process on a collaborative supply chain basis is one of his major passions.

Welcome Remarks

B. Weiss
Chief of Staff & Corporate Strategy
SEMI, Milpitas, California, United States of

America



Abstract

Coming Soon

Biography

As Chief of Staff & Corporate Strategy, Bettina Weiss reports to SEMI's President & CEO and manages a broad portfolio of responsibilities. Major focus areas include advancing specific global strategic initiatives such as SEMI's Smart Mobility and Supply Chain initiatives and SEMI University, facilitate thought leadership (Think Tanks) activities in key strategic areas as well as improving organizational efficiency, alignment and financial sustainability. In addition, Weiss is the Sr. Liaison to the SEMI Board of Industry Leaders, leading strategic partnerships and M&A activity, and supporting the President & CEO in successfully creating a highly effective, agile global association.

Weiss joined SEMI in 1996 and held a variety of positions in SEMI's International Standards department, including department lead, global responsibility for SEMI's Photovoltaic/Solar Business Unit, business development including the integration of SEMI Strategic Association Partners FlexTech, MEMS & Sensors Industry Group, ESD Alliance and the SOI Consortium.

Prior to joining SEMI, Weiss worked in sales and marketing positions at Metron Semiconductor and Varian Semiconductor in Munich, Germany. She holds a BA from the International School for Applied Languages in Munich, Germany, and is a certified translator for Anglo-American Law and Economics.

Topic Coming Soon



M. Stigall
SVP Global Fab Operations
Wolfspeed, McKinney, United States of America



Abstract

Coming Soon

Biography

Missy is responsible for the strategy and direction of the Wolfspeed global device factories, developing innovative production solutions, building dynamic manufacturing and engineering teams, and delivering on-time quality execution that meets customer needs. In addition, she sponsors our Management of Change initiative, is responsible for several initiatives in the Global Ops organization, and has a passion for driving critical conversations that result in solutions that evolve inclusion and diversity.

Missy has 25 years of experience in the semiconductor industry, encompassing a wide range of roles. She graduated from Southern Methodist University with a BS in Electrical Engineering and from Kettering University with a MS in Engineering Management.

Opening Remarks



A. Aal
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Topic Coming Soon



M. Schmid
Senior Director Purchasing Group / Brand
Semiconductor Management
Volkswagen AG, Munich, Germany



Abstract

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Biography

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The Future of Advanced Packaging Inspection is X-Ray



D. van de Ven
President of the Industrial X-Ray Systems (IXS)
Division
Comet, Hamburg, Germany



Abstract

Key take aways:

- Semiconductor industry is driven by miniaturization & efficiency
- Next generation X-Ray as valuable inspection method for Advanced packaging
- X-Ray as booster for faster time-to-market & increased yield

In Summary:

X-Ray technology is ready as a valuable inspection solution for Advanced Packaging to reduce time-to-market and increase yield.

Biography

Dionys van de Ven
President Industrial X-Ray Systems

Born 1968, Dutch citizen; Master's degree in mechanical engineering from the Eindhoven University of Technology, Eindhoven

Before joining Comet in 2022, Dionys van de Ven has led Waygate Technologies' x-ray business unit (part of Baker Hughes) as the unit's Business Executive since 2020. In addition, he has been serving as Managing Director of Baker Hughes Digital Solutions GmbH and member of the board of management of GE Inspection Robotics.

Dionys van de Ven began his career at Philips Assembléon in 1997. In 2005 he became Director of Customer Relationship Management at Philips Applied Technologies and, in 2007, Senior Director of Customer Programs, Service and R&D at Philips Healthcare. In 2017, he joined Waygate Technologies.